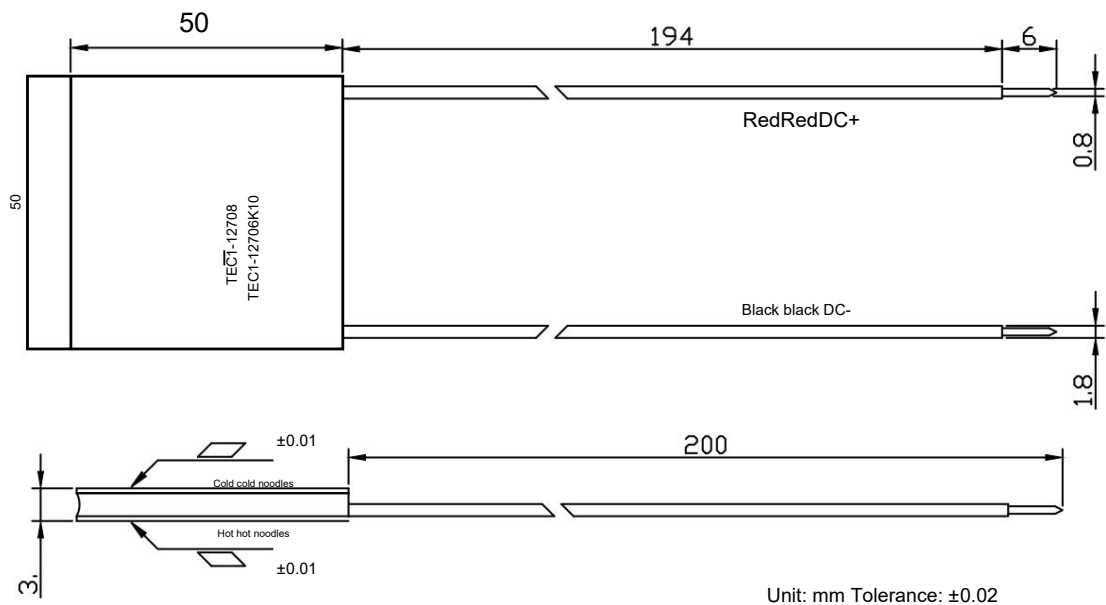


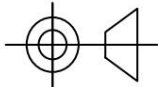
Semiconductor refrigeration chip specifications

TEC1-12708

1. Dimensions



2. Performance indicators

Product	Model	TEC1-12708	Dimensions	Size	50x50x4.5mm	
Maximum voltage	Vmax	DC15.2V	Internal resistance	Impe	1.98Ω	
Maximum current	Imax	8A	Solder type	Solder	Bi67+Sn33	
Maximum temperature difference	DTmax	60℃	Packaging material	materia	96% alumina+CU2	
Input power	Wmax	96W	Sealing material	Seal up	704 silicone rubber	
Cooling capacity	Cool	74.8W	Lead specifications Wire standard	Wire gauge	length	terminal
Maximum temperature resistance	Kmax	≤150℃		UL1007	+Red 200	NO
				18AGW	-Black 200	
			Making orders	Name	Huang Dong	
			Update date	Date	2023-01-09	
Thermoelectric Cooler						